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Understanding Embedded - CPLDs (Complex Programmable Logic Devices)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details	
Product Status	Obsolete
Programmable Type	EE PLD
Delay Time tpd(1) Max	12 ns
Voltage Supply - Internal	4.75V ~ 5.25V
Number of Logic Elements/Blocks	6
Number of Macrocells	96
Number of Gates	1800
Number of I/O	52
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	68-LCC (J-Lead)
Supplier Device Package	68-PLCC (24x24)
Purchase URL	https://www.e-xfl.com/product-detail/intel/epm7096lc68-12

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

Table 2. MAX 7000S Device Features								
Feature	EPM7032S	EPM7064S	EPM7128S	EPM7160S	EPM7192S	EPM7256S		
Usable gates	600	1,250	2,500	3,200	3,750	5,000		
Macrocells	32	64	128	160	192	256		
Logic array blocks	2	4	8	10	12	16		
Maximum user I/O pins	36	68	100	104	124	164		
t _{PD} (ns)	5	5	6	6	7.5	7.5		
t _{SU} (ns)	2.9	2.9	3.4	3.4	4.1	3.9		
t _{FSU} (ns)	2.5	2.5	2.5	2.5	3	3		
t _{CO1} (ns)	3.2	3.2	4	3.9	4.7	4.7		
f _{CNT} (MHz)	175.4	175.4	147.1	149.3	125.0	128.2		

...and More Features

- Open-drain output option in MAX 7000S devices
- Programmable macrocell flipflops with individual clear, preset, clock, and clock enable controls
- Programmable power-saving mode for a reduction of over 50% in each macrocell
- Configurable expander product-term distribution, allowing up to 32 product terms per macrocell
- 44 to 208 pins available in plastic J-lead chip carrier (PLCC), ceramic pin-grid array (PGA), plastic quad flat pack (PQFP), power quad flat pack (RQFP), and 1.0-mm thin quad flat pack (TQFP) packages
- Programmable security bit for protection of proprietary designs
- 3.3-V or 5.0-V operation
 - MultiVoltTM I/O interface operation, allowing devices to interface with 3.3-V or 5.0-V devices (MultiVolt I/O operation is not available in 44-pin packages)
 - Pin compatible with low-voltage MAX 7000A and MAX 7000B devices
- Enhanced features available in MAX 7000E and MAX 7000S devices
 - Six pin- or logic-driven output enable signals
 - Two global clock signals with optional inversion
 - Enhanced interconnect resources for improved routability
 - Fast input setup times provided by a dedicated path from I/O pin to macrocell registers
 - Programmable output slew-rate control
- Software design support and automatic place-and-route provided by Altera's development system for Windows-based PCs and Sun SPARCstation, and HP 9000 Series 700/800 workstations

The MAX 7000E devices—including the EPM7128E, EPM7160E, EPM7192E, and EPM7256E devices—have several enhanced features: additional global clocking, additional output enable controls, enhanced interconnect resources, fast input registers, and a programmable slew rate.

In-system programmable MAX 7000 devices—called MAX 7000S devices—include the EPM7032S, EPM7064S, EPM7128S, EPM7160S, EPM7192S, and EPM7256S devices. MAX 7000S devices have the enhanced features of MAX 7000E devices as well as JTAG BST circuitry in devices with 128 or more macrocells, ISP, and an open-drain output option. See Table 4.

Table 4. MAX 7000 Device Features						
Feature	EPM7032 EPM7064 EPM7096	All MAX 7000E Devices	All MAX 7000S Devices			
ISP via JTAG interface			✓			
JTAG BST circuitry			√ (1)			
Open-drain output option			✓			
Fast input registers		✓	✓			
Six global output enables		✓	✓			
Two global clocks		✓	✓			
Slew-rate control		✓	✓			
MultiVolt interface (2)	✓	✓	✓			
Programmable register	✓	✓	✓			
Parallel expanders	✓	✓	✓			
Shared expanders	✓	✓	✓			
Power-saving mode	✓	✓	✓			
Security bit	✓	✓	✓			
PCI-compliant devices available	✓	✓	✓			

Notes:

- (1) Available only in EPM7128S, EPM7160S, EPM7192S, and EPM7256S devices only.
- (2) The MultiVolt I/O interface is not available in 44-pin packages.

The MAX 7000 architecture includes four dedicated inputs that can be used as general-purpose inputs or as high-speed, global control signals (clock, clear, and two output enable signals) for each macrocell and I/O pin. Figure 1 shows the architecture of EPM7032, EPM7064, and EPM7096 devices.

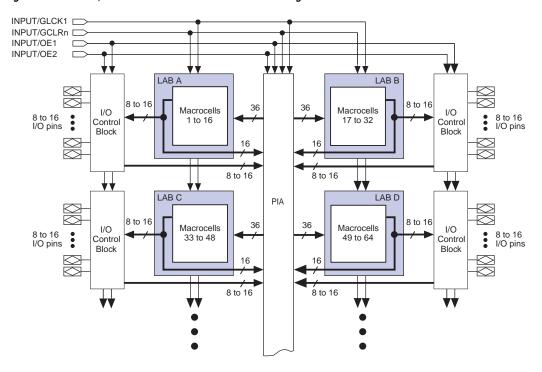


Figure 1. EPM7032, EPM7064 & EPM7096 Device Block Diagram

Each programmable register can be clocked in three different modes:

- By a global clock signal. This mode achieves the fastest clock-tooutput performance.
- By a global clock signal and enabled by an active-high clock enable. This mode provides an enable on each flipflop while still achieving the fast clock-to-output performance of the global clock.
- By an array clock implemented with a product term. In this mode, the flipflop can be clocked by signals from buried macrocells or I/O pins.

In EPM7032, EPM7064, and EPM7096 devices, the global clock signal is available from a dedicated clock pin, GCLK1, as shown in Figure 1. In MAX 7000E and MAX 7000S devices, two global clock signals are available. As shown in Figure 2, these global clock signals can be the true or the complement of either of the global clock pins, GCLK1 or GCLK2.

Each register also supports asynchronous preset and clear functions. As shown in Figures 3 and 4, the product-term select matrix allocates product terms to control these operations. Although the product-term-driven preset and clear of the register are active high, active-low control can be obtained by inverting the signal within the logic array. In addition, each register clear function can be individually driven by the active-low dedicated global clear pin (GCLRn). Upon power-up, each register in the device will be set to a low state.

All MAX 7000E and MAX 7000S I/O pins have a fast input path to a macrocell register. This dedicated path allows a signal to bypass the PIA and combinatorial logic and be driven to an input D flipflop with an extremely fast (2.5 ns) input setup time.

Expander Product Terms

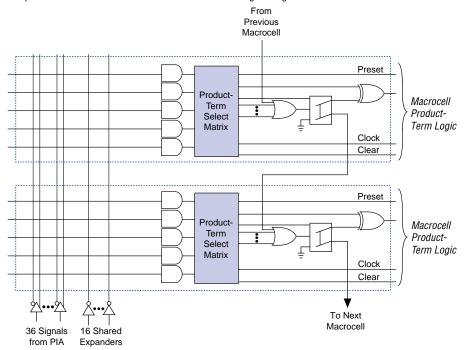
Although most logic functions can be implemented with the five product terms available in each macrocell, the more complex logic functions require additional product terms. Another macrocell can be used to supply the required logic resources; however, the MAX 7000 architecture also allows both shareable and parallel expander product terms ("expanders") that provide additional product terms directly to any macrocell in the same LAB. These expanders help ensure that logic is synthesized with the fewest possible logic resources to obtain the fastest possible speed.

The compiler can allocate up to three sets of up to five parallel expanders automatically to the macrocells that require additional product terms. Each set of five parallel expanders incurs a small, incremental timing delay (t_{PEXP}). For example, if a macrocell requires 14 product terms, the Compiler uses the five dedicated product terms within the macrocell and allocates two sets of parallel expanders; the first set includes five product terms and the second set includes four product terms, increasing the total delay by $2 \times t_{PEXP}$.

Two groups of 8 macrocells within each LAB (e.g., macrocells 1 through 8 and 9 through 16) form two chains to lend or borrow parallel expanders. A macrocell borrows parallel expanders from lower-numbered macrocells. For example, macrocell 8 can borrow parallel expanders from macrocell 7, from macrocells 7 and 6, or from macrocells 7, 6, and 5. Within each group of 8, the lowest-numbered macrocell can only lend parallel expanders and the highest-numbered macrocell can only borrow them. Figure 6 shows how parallel expanders can be borrowed from a neighboring macrocell.

Figure 6. Parallel Expanders

Unused product terms in a macrocell can be allocated to a neighboring macrocell.





For more information on using the Jam language, refer to AN 122: Using Jam STAPL for ISP & ICR via an Embedded Processor.

The ISP circuitry in MAX 7000S devices is compatible with IEEE Std. 1532 specification. The IEEE Std. 1532 is a standard developed to allow concurrent ISP between multiple PLD vendors.

Programming Sequence

During in-system programming, instructions, addresses, and data are shifted into the MAX 7000S device through the TDI input pin. Data is shifted out through the TDO output pin and compared against the expected data.

Programming a pattern into the device requires the following six ISP stages. A stand-alone verification of a programmed pattern involves only stages 1, 2, 5, and 6.

- Enter ISP. The enter ISP stage ensures that the I/O pins transition smoothly from user mode to ISP mode. The enter ISP stage requires 1 ms.
- 2. *Check ID*. Before any program or verify process, the silicon ID is checked. The time required to read this silicon ID is relatively small compared to the overall programming time.
- 3. *Bulk Erase*. Erasing the device in-system involves shifting in the instructions to erase the device and applying one erase pulse of 100 ms.
- Program. Programming the device in-system involves shifting in the address and data and then applying the programming pulse to program the EEPROM cells. This process is repeated for each EEPROM address.
- Verify. Verifying an Altera device in-system involves shifting in addresses, applying the read pulse to verify the EEPROM cells, and shifting out the data for comparison. This process is repeated for each EEPROM address.
- 6. Exit ISP. An exit ISP stage ensures that the I/O pins transition smoothly from ISP mode to user mode. The exit ISP stage requires 1 ms.

Programming Times

The time required to implement each of the six programming stages can be broken into the following two elements:

- A pulse time to erase, program, or read the EEPROM cells.
- A shifting time based on the test clock (TCK) frequency and the number of TCK cycles to shift instructions, address, and data into the device.

By combining the pulse and shift times for each of the programming stages, the program or verify time can be derived as a function of the TCK frequency, the number of devices, and specific target device(s). Because different ISP-capable devices have a different number of EEPROM cells, both the total fixed and total variable times are unique for a single device.

Programming a Single MAX 7000S Device

The time required to program a single MAX 7000S device in-system can be calculated from the following formula:

$$t_{PROG} = t_{PPULSE} + \frac{Cycle_{PTCK}}{f_{TCK}}$$

where: t_{PROG} = Programming time t_{PPULSE} = Sum of the fixed times to erase, program, and

verify the EEPROM cells

 $Cycle_{PTCK}$ = Number of TCK cycles to program a device

= TCK frequency

The ISP times for a stand-alone verification of a single MAX 7000S device can be calculated from the following formula:

$$t_{VER} = t_{VPULSE} + \frac{Cycle_{VTCK}}{f_{TCK}}$$

where: t_{VER} = Verify time

 t_{VPULSE} = Sum of the fixed times to verify the EEPROM cells

 $Cycle_{VTCK}$ = Number of TCK cycles to verify a device

The programming times described in Tables 6 through 8 are associated with the worst-case method using the enhanced ISP algorithm.

Table 6. MAX 7000S t _{PULSE} & Cycle _{TCK} Values							
Device	Progra	ımming	Stand-Alone Verification				
	t _{PPULSE} (s)	Cycle _{PTCK}	t _{VPULSE} (s)	Cycle _{VTCK}			
EPM7032S	4.02	342,000	0.03	200,000			
EPM7064S	4.50	504,000	0.03	308,000			
EPM7128S	5.11	832,000	0.03	528,000			
EPM7160S	5.35	1,001,000	0.03	640,000			
EPM7192S	5.71	1,192,000	0.03	764,000			
EPM7256S	6.43	1,603,000	0.03	1,024,000			

Tables 7 and 8 show the in-system programming and stand alone verification times for several common test clock frequencies.

Table 7. MAX 7000S In-System Programming Times for Different Test Clock Frequencies									
Device		f _{TCK}							Units
	10 MHz	5 MHz	2 MHz	1 MHz	500 kHz	200 kHz	100 kHz	50 kHz	
EPM7032S	4.06	4.09	4.19	4.36	4.71	5.73	7.44	10.86	s
EPM7064S	4.55	4.60	4.76	5.01	5.51	7.02	9.54	14.58	S
EPM7128S	5.19	5.27	5.52	5.94	6.77	9.27	13.43	21.75	S
EPM7160S	5.45	5.55	5.85	6.35	7.35	10.35	15.36	25.37	S
EPM7192S	5.83	5.95	6.30	6.90	8.09	11.67	17.63	29.55	S
EPM7256S	6.59	6.75	7.23	8.03	9.64	14.45	22.46	38.49	S

Table 8. MAX 7000S Stand-Alone Verification Times for Different Test Clock Frequencies									
Device		f _{TCK}							Units
	10 MHz	5 MHz	2 MHz	1 MHz	500 kHz	200 kHz	100 kHz	50 kHz	
EPM7032S	0.05	0.07	0.13	0.23	0.43	1.03	2.03	4.03	s
EPM7064S	0.06	0.09	0.18	0.34	0.64	1.57	3.11	6.19	S
EPM7128S	0.08	0.14	0.29	0.56	1.09	2.67	5.31	10.59	S
EPM7160S	0.09	0.16	0.35	0.67	1.31	3.23	6.43	12.83	S
EPM7192S	0.11	0.18	0.41	0.79	1.56	3.85	7.67	15.31	S
EPM7256S	0.13	0.24	0.54	1.06	2.08	5.15	10.27	20.51	S

Programmable Speed/Power Control

MAX 7000 devices offer a power-saving mode that supports low-power operation across user-defined signal paths or the entire device. This feature allows total power dissipation to be reduced by 50% or more, because most logic applications require only a small fraction of all gates to operate at maximum frequency.

The designer can program each individual macrocell in a MAX 7000 device for either high-speed (i.e., with the Turbo BitTM option turned on) or low-power (i.e., with the Turbo Bit option turned off) operation. As a result, speed-critical paths in the design can run at high speed, while the remaining paths can operate at reduced power. Macrocells that run at low power incur a nominal timing delay adder (t_{LPA}) for the t_{LAD} , t_{LAC} , t_{IC} , t_{EN} , and t_{SEXP} , t_{ACL} , and t_{CPPW} parameters.

Output Configuration

MAX 7000 device outputs can be programmed to meet a variety of system-level requirements.

MultiVolt I/O Interface

MAX 7000 devices—except 44-pin devices—support the MultiVolt I/O interface feature, which allows MAX 7000 devices to interface with systems that have differing supply voltages. The 5.0-V devices in all packages can be set for 3.3-V or 5.0-V I/O pin operation. These devices have one set of VCC pins for internal operation and input buffers (VCCINT), and another set for I/O output drivers (VCCIO).

The VCCINT pins must always be connected to a 5.0-V power supply. With a 5.0-V $V_{\rm CCINT}$ level, input voltage thresholds are at TTL levels, and are therefore compatible with both 3.3-V and 5.0-V inputs.

The VCCIO pins can be connected to either a 3.3-V or a 5.0-V power supply, depending on the output requirements. When the VCCIO pins are connected to a 5.0-V supply, the output levels are compatible with 5.0-V systems. When $V_{\rm CCIO}$ is connected to a 3.3-V supply, the output high is 3.3 V and is therefore compatible with 3.3-V or 5.0-V systems. Devices operating with $V_{\rm CCIO}$ levels lower than 4.75 V incur a nominally greater timing delay of $t_{\rm OD2}$ instead of $t_{\rm OD1}$.

Open-Drain Output Option (MAX 7000S Devices Only)

MAX 7000S devices provide an optional open-drain (functionally equivalent to open-collector) output for each I/O pin. This open-drain output enables the device to provide system-level control signals (e.g., interrupt and write enable signals) that can be asserted by any of several devices. It can also provide an additional wired-OR plane.

By using an external 5.0-V pull-up resistor, output pins on MAX 7000S devices can be set to meet 5.0-V CMOS input voltages. When $V_{\rm CCIO}$ is 3.3 V, setting the open drain option will turn off the output pull-up transistor, allowing the external pull-up resistor to pull the output high enough to meet 5.0-V CMOS input voltages. When $V_{\rm CCIO}$ is 5.0 V, setting the output drain option is not necessary because the pull-up transistor will already turn off when the pin exceeds approximately 3.8 V, allowing the external pull-up resistor to pull the output high enough to meet 5.0-V CMOS input voltages.

Slew-Rate Control

The output buffer for each MAX 7000E and MAX 7000S I/O pin has an adjustable output slew rate that can be configured for low-noise or high-speed performance. A faster slew rate provides high-speed transitions for high-performance systems. However, these fast transitions may introduce noise transients into the system. A slow slew rate reduces system noise, but adds a nominal delay of 4 to 5 ns. In MAX 7000E devices, when the Turbo Bit is turned off, the slew rate is set for low noise performance. For MAX 7000S devices, each I/O pin has an individual EEPROM bit that controls the slew rate, allowing designers to specify the slew rate on a pin-by-pin basis.

Programming with External Hardware

MAX 7000 devices can be programmed on Windows-based PCs with the Altera Logic Programmer card, the Master Programming Unit (MPU), and the appropriate device adapter. The MPU performs a continuity check to ensure adequate electrical contact between the adapter and the device.



For more information, see the *Altera Programming Hardware Data Sheet*.

The Altera development system can use text- or waveform-format test vectors created with the Text Editor or Waveform Editor to test the programmed device. For added design verification, designers can perform functional testing to compare the functional behavior of a MAX 7000 device with the results of simulation. Moreover, Data I/O, BP Microsystems, and other programming hardware manufacturers also provide programming support for Altera devices.



For more information, see the *Programming Hardware Manufacturers*.

The instruction register length of MAX 7000S devices is 10 bits. Tables 10 and 11 show the boundary-scan register length and device IDCODE information for MAX 7000S devices.

Table 10. MAX 7000S Boundary-Scan Register Length						
Device Boundary-Scan Register Length						
EPM7032S	1 (1)					
EPM7064S	1 (1)					
EPM7128S	288					
EPM7160S	312					
EPM7192S	360					
EPM7256S	480					

Note:

(1) This device does not support JTAG boundary-scan testing. Selecting either the EXTEST or SAMPLE/PRELOAD instruction will select the one-bit bypass register.

Table 11. 32-Bit MAX 7000 Device IDCODE Note (1)								
Device		IDCODE (32 Bits)						
	Version (4 Bits)	Part Number (16 Bits)	Manufacturer's Identity (11 Bits)	1 (1 Bit) (2)				
EPM7032S	0000	0111 0000 0011 0010	00001101110	1				
EPM7064S	0000	0111 0000 0110 0100	00001101110	1				
EPM7128S	0000	0111 0001 0010 1000	00001101110	1				
EPM7160S	0000	0111 0001 0110 0000	00001101110	1				
EPM7192S	0000	0111 0001 1001 0010	00001101110	1				
EPM7256S	0000	0111 0010 0101 0110	00001101110	1				

Notes:

- (1) The most significant bit (MSB) is on the left.
- (2) The least significant bit (LSB) for all JTAG IDCODEs is 1.

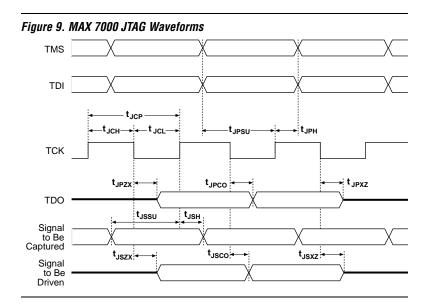


Figure 9 shows the timing requirements for the JTAG signals.

Table 12 shows the JTAG timing parameters and values for MAX 7000S devices.

Table 12. JTAG Timing Parameters & Values for MAX 7000S Devices							
Symbol	Parameter	Min	Max	Unit			
t _{JCP}	TCK clock period	100		ns			
t _{JCH}	TCK clock high time	50		ns			
t _{JCL}	TCK clock low time	50		ns			
t _{JPSU}	JTAG port setup time	20		ns			
t _{JPH}	JTAG port hold time	45		ns			
t _{JPCO}	JTAG port clock to output		25	ns			
t _{JPZX}	JTAG port high impedance to valid output		25	ns			
t _{JPXZ}	JTAG port valid output to high impedance		25	ns			
t _{JSSU}	Capture register setup time	20		ns			
t _{JSH}	Capture register hold time	45		ns			
t _{JSCO}	Update register clock to output		25	ns			
t _{JSZX}	Update register high impedance to valid output		25	ns			
t _{JSXZ}	Update register valid output to high impedance		25	ns			



For more information, see *Application Note* 39 (*IEEE 1149.1 (JTAG) Boundary-Scan Testing in Altera Devices*).

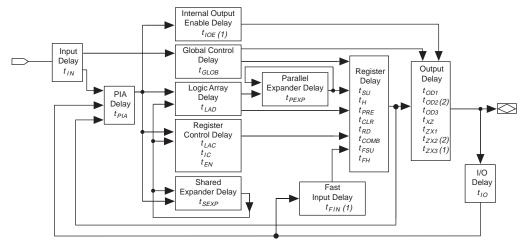
Symbol	Parameter	Conditions	Min	Max	Unit
V _{IH}	High-level input voltage		2.0	V _{CCINT} + 0.5	V
V _{IL}	Low-level input voltage		-0.5 (8)	0.8	V
V _{OH}	5.0-V high-level TTL output voltage	$I_{OH} = -4 \text{ mA DC}, V_{CCIO} = 4.75 \text{ V } (10)$	2.4		V
	3.3-V high-level TTL output voltage	$I_{OH} = -4 \text{ mA DC}, V_{CCIO} = 3.00 \text{ V } (10)$	2.4		V
	3.3-V high-level CMOS output voltage	$I_{OH} = -0.1 \text{ mA DC}, V_{CCIO} = 3.0 \text{ V } (10)$	V _{CCIO} - 0.2		V
V _{OL}	5.0-V low-level TTL output voltage	I _{OL} = 12 mA DC, V _{CCIO} = 4.75 V (11)		0.45	V
	3.3-V low-level TTL output voltage	I _{OL} = 12 mA DC, V _{CCIO} = 3.00 V (11)		0.45	V
	3.3-V low-level CMOS output voltage	$I_{OL} = 0.1 \text{ mA DC}, V_{CCIO} = 3.0 \text{ V}(11)$		0.2	V
I _I	Leakage current of dedicated input pins	V _I = -0.5 to 5.5 V (11)	-10	10	μА
l _{OZ}	I/O pin tri-state output off-state current	V _I = -0.5 to 5.5 V (11), (12)	-40	40	μА

Table 16. MAX 7000 5.0-V Device Capacitance: EPM7032, EPM7064 & EPM7096 Devices					
Symbol	Parameter	Conditions	Min	Max	Unit
C _{IN}	Input pin capacitance	V _{IN} = 0 V, f = 1.0 MHz		12	pF
C _{I/O}	I/O pin capacitance	V _{OUT} = 0 V, f = 1.0 MHz		12	pF

Table 1	Table 17. MAX 7000 5.0-V Device Capacitance: MAX 7000E DevicesNote (13)								
Symbol	Parameter	Conditions	Min	Max	Unit				
C _{IN}	Input pin capacitance	V _{IN} = 0 V, f = 1.0 MHz		15	pF				
C _{I/O}	I/O pin capacitance	V _{OUT} = 0 V, f = 1.0 MHz		15	pF				

Table 18. MAX 7000 5.0-V Device Capacitance: MAX 7000S Devices Note (13)								
Symbol	Parameter	Conditions	Min	Max	Unit			
C _{IN}	Dedicated input pin capacitance	V _{IN} = 0 V, f = 1.0 MHz		10	pF			
C _{I/O}	I/O pin capacitance	V _{OUT} = 0 V, f = 1.0 MHz		10	pF			

Figure 12. MAX 7000 Timing Model



Notes:

- (1) Only available in MAX 7000E and MAX 7000S devices.
- (2) Not available in 44-pin devices.

The timing characteristics of any signal path can be derived from the timing model and parameters of a particular device. External timing parameters, which represent pin-to-pin timing delays, can be calculated as the sum of internal parameters. Figure 13 shows the internal timing relationship of internal and external delay parameters.



For more infomration, see *Application Note* 94 (*Understanding MAX* 7000 *Timing*).

Symbol	Parameter	Conditions	Speed Grade									
			-	-5		-6		7	-10			
			Min	Max	Min	Max	Min	Max	Min	Max		
t _{FSU}	Register setup time of fast input		1.9		1.8		3.0		3.0		ns	
t _{FH}	Register hold time of fast input		0.6		0.7		0.5		0.5		ns	
t _{RD}	Register delay			1.2		1.6		1.0		2.0	ns	
t _{COMB}	Combinatorial delay			0.9		1.0		1.0		2.0	ns	
t _{IC}	Array clock delay			2.7		3.3		3.0		5.0	ns	
t _{EN}	Register enable time			2.6		3.2		3.0		5.0	ns	
t_{GLOB}	Global control delay			1.6		1.9		1.0		1.0	ns	
t _{PRE}	Register preset time			2.0		2.4		2.0		3.0	ns	
t _{CLR}	Register clear time			2.0		2.4		2.0		3.0	ns	
t _{PIA}	PIA delay	(7)		1.1		1.3		1.0		1.0	ns	
t_{LPA}	Low-power adder	(8)		12.0		11.0		10.0		11.0	ns	

- (1) These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
- (2) This minimum pulse width for preset and clear applies for both global clear and array controls. The t_{LPA} parameter must be added to this minimum width if the clear or reset signal incorporates the t_{LAD} parameter into the signal path.
- (3) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (4) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (5) The f_{MAX} values represent the highest frequency for pipelined data.
- (6) Operating conditions: $V_{CCIO} = 3.3 \text{ V} \pm 10\%$ for commercial and industrial use.
- (7) For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.
- (8) The t_{LPA} parameter must be added to the t_{LAD} , t_{LAC} , t_{IC} , t_{EN} , t_{SEXP} , $\mathbf{t_{ACL}}$, and $\mathbf{t_{CPPW}}$ parameters for macrocells running in the low-power mode.

Tables 31 and 32 show the EPM7128S AC operating conditions.

Table 3	11. EPM7128\$ External Time	ing Parameters	: No	te (1)							
Symbol	Parameter	Conditions	Speed Grade								
			-6		-7		-10		-15		
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{PD1}	Input to non-registered output	C1 = 35 pF		6.0		7.5		10.0		15.0	ns
t _{PD2}	I/O input to non-registered output	C1 = 35 pF		6.0		7.5		10.0		15.0	ns
t _{SU}	Global clock setup time		3.4		6.0		7.0		11.0		ns
t _H	Global clock hold time		0.0		0.0		0.0		0.0		ns
t _{FSU}	Global clock setup time of fast input		2.5		3.0		3.0		3.0		ns
t _{FH}	Global clock hold time of fast input		0.0		0.5		0.5		0.0		ns
t _{CO1}	Global clock to output delay	C1 = 35 pF		4.0		4.5		5.0		8.0	ns
t _{CH}	Global clock high time		3.0		3.0		4.0		5.0		ns
t _{CL}	Global clock low time		3.0		3.0		4.0		5.0		ns
t _{ASU}	Array clock setup time		0.9		3.0		2.0		4.0		ns
t _{AH}	Array clock hold time		1.8		2.0		5.0		4.0		ns
t _{ACO1}	Array clock to output delay	C1 = 35 pF		6.5		7.5		10.0		15.0	ns
t _{ACH}	Array clock high time		3.0		3.0		4.0		6.0		ns
t _{ACL}	Array clock low time		3.0		3.0		4.0		6.0		ns
t _{CPPW}	Minimum pulse width for clear and preset	(2)	3.0		3.0		4.0		6.0		ns
t _{ODH}	Output data hold time after clock	C1 = 35 pF (3)	1.0		1.0		1.0		1.0		ns
t _{CNT}	Minimum global clock period			6.8		8.0		10.0		13.0	ns
f _{CNT}	Maximum internal global clock frequency	(4)	147.1		125.0		100.0		76.9		MHz
t _{ACNT}	Minimum array clock period			6.8		8.0		10.0		13.0	ns
f _{ACNT}	Maximum internal array clock frequency	(4)	147.1		125.0		100.0		76.9		MHz
f _{MAX}	Maximum clock frequency	(5)	166.7		166.7		125.0		100.0		MHz

Table 34. EPM7160S Internal Timing Parameters (Part 2 of 2) Note (1)											
Symbol	Parameter	Conditions	Speed Grade								
			-	-6 -7				10	-1		
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{CLR}	Register clear time			2.4		3.0		3.0		4.0	ns
t _{PIA}	PIA delay	(7)		1.6		2.0		1.0		2.0	ns
t _{LPA}	Low-power adder	(8)		11.0		10.0		11.0		13.0	ns

- These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
- (2) This minimum pulse width for preset and clear applies for both global clear and array controls. The t_{LPA} parameter must be added to this minimum width if the clear or reset signal incorporates the t_{LAD} parameter into the signal path.
- (3) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (4) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (5) The f_{MAX} values represent the highest frequency for pipelined data.
- (6) Operating conditions: $V_{CCIO} = 3.3 \text{ V} \pm 10\%$ for commercial and industrial use.
- (7) For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.
- (8) The t_{LPA} parameter must be added to the t_{LAD} , t_{LAC} , t_{IC} , t_{EN} , t_{SEXP} , t_{ACL} , and t_{CPPW} parameters for macrocells running in the low-power mode.

Tables 35 and 36 show the EPM7192S AC operating conditions.

Table 3	Table 35. EPM7192S External Timing Parameters (Part 1 of 2) Note (1)										
Symbol	Parameter	Conditions	Speed Grade								
			-7		-10		-15				
			Min	Max	Min	Max	Min	Max			
t _{PD1}	Input to non-registered output	C1 = 35 pF		7.5		10.0		15.0	ns		
t _{PD2}	I/O input to non-registered output	C1 = 35 pF		7.5		10.0		15.0	ns		
t _{SU}	Global clock setup time		4.1		7.0		11.0		ns		
t _H	Global clock hold time		0.0		0.0		0.0		ns		
t _{FSU}	Global clock setup time of fast input		3.0		3.0		3.0		ns		
t _{FH}	Global clock hold time of fast input		0.0		0.5		0.0		ns		
t _{CO1}	Global clock to output delay	C1 = 35 pF		4.7		5.0		8.0	ns		
t _{CH}	Global clock high time		3.0		4.0		5.0		ns		
t _{CL}	Global clock low time		3.0		4.0		5.0		ns		
t _{ASU}	Array clock setup time		1.0		2.0		4.0		ns		

Table 36. EPM7192S Internal Timing Parameters (Part 2 of 2) Note (1)											
Symbol	Parameter	Conditions		Speed Grade							
				-7		10	-15				
			Min	Max	Min	Max	Min	Max	1		
t _H	Register hold time		1.7		3.0		4.0		ns		
t _{FSU}	Register setup time of fast input		2.3		3.0		2.0		ns		
t _{FH}	Register hold time of fast input		0.7		0.5		1.0		ns		
t _{RD}	Register delay			1.4		2.0		1.0	ns		
t _{COMB}	Combinatorial delay			1.2		2.0		1.0	ns		
t_{IC}	Array clock delay			3.2		5.0		6.0	ns		
t _{EN}	Register enable time			3.1		5.0		6.0	ns		
t_{GLOB}	Global control delay			2.5		1.0		1.0	ns		
t _{PRE}	Register preset time			2.7		3.0		4.0	ns		
t _{CLR}	Register clear time			2.7		3.0		4.0	ns		
t _{PIA}	PIA delay	(7)		2.4		1.0		2.0	ns		
t_{LPA}	Low-power adder	(8)		10.0		11.0		13.0	ns		

- These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
- (2) This minimum pulse width for preset and clear applies for both global clear and array controls. The t_{LPA} parameter must be added to this minimum width if the clear or reset signal incorporates the t_{LAD} parameter into the signal path.
- (3) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (4) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (5) The f_{MAX} values represent the highest frequency for pipelined data.
- (6) Operating conditions: $V_{CCIO} = 3.3 \text{ V} \pm 10\%$ for commercial and industrial use.
- (7) For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.
- (8) The t_{LPA} parameter must be added to the t_{LAD} , t_{LAC} , t_{IC} , t_{EN} , t_{SEXP} , $\mathbf{t_{ACL}}$, and $\mathbf{t_{CPPW}}$ parameters for macrocells running in the low-power mode.

- These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
- (2) This minimum pulse width for preset and clear applies for both global clear and array controls. The t_{LPA} parameter must be added to this minimum width if the clear or reset signal incorporates the t_{LAD} parameter into the signal path.
- (3) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (4) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (5) The f_{MAX} values represent the highest frequency for pipelined data.
- (6) Operating conditions: $V_{CCIO} = 3.3 \text{ V} \pm 10\%$ for commercial and industrial use.
- (7) For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.
- (8) The t_{LPA} parameter must be added to the t_{LAD} , t_{LAC} , t_{IC} , t_{EN} , t_{SEXP} , $\mathbf{t_{ACL}}$, and $\mathbf{t_{CPPW}}$ parameters for macrocells running in the low-power mode.

Power Consumption

Supply power (P) versus frequency (f_{MAX} in MHz) for MAX 7000 devices is calculated with the following equation:

$$P = P_{INT} + P_{IO} = I_{CCINT} \times V_{CC} + P_{IO}$$

The P_{IO} value, which depends on the device output load characteristics and switching frequency, can be calculated using the guidelines given in *Application Note* 74 (*Evaluating Power for Altera Devices*).

The I_{CCINT} value, which depends on the switching frequency and the application logic, is calculated with the following equation:

$$I_{CCINT} =$$

$$A \times MC_{TON} + B \times (MC_{DEV} - MC_{TON}) + C \times MC_{USED} \times f_{MAX} \times tog_{USED}$$

The parameters in this equation are shown below:

 MC_{TON} = Number of macrocells with the Turbo Bit option turned on,

as reported in the MAX+PLUS II Report File (.rpt)

 MC_{DEV} = Number of macrocells in the device

 MC_{LISED} = Total number of macrocells in the design, as reported

in the MAX+PLUS II Report File (.rpt)

 f_{MAX} = Highest clock frequency to the device

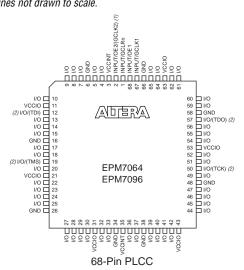
tog_{LC} = Average ratio of logic cells toggling at each clock

(typically 0.125)

A, B, C = Constants, shown in Table 39

Figure 17. 68-Pin Package Pin-Out Diagram

Package outlines not drawn to scale.



Notes:

- The pin functions shown in parenthesis are only available in MAX 7000E and MAX 7000S devices.
- (2) JTAG ports are available in MAX 7000S devices only.